

Key Features

Bonds Well to Most Substrates
Electrically Isolating
Gap Filling
Meets NASA Outgassing
HMS 2240, Type IX
Low Shrinkage
Room or Elevated Temperature Cure
User-friendly Packaging

Uncured

Viscosity @ 25°C: 55,000 cPs
Thixotropic Index: 1.0
Pot Life @ 25°C: 1 hour
Shelf Life @ -40°C: 6 Months

Cure Options

1 hour @ 93°C
7 days @ 25°C

Cured Properties

(Based on cure of 1 hours @ 93°C)

Color	Green
Shore D Hardness	88
Glass Transition Temp (°C)	87
Lap Shear 2024T3 Clad (psi)	3,500

Electrical Properties

(Based on cure of 1 hours @ 93°C)

Dielectric Constant	3.4 @ 1000 Hz
Dissipation Factor	0.05 @ 1000 Hz
Volume Resistivity (ohm-cm)	1.0E 15 @ 500 VDC

Product Description:

0161 is a one-component, slightly thixotropic, electrically isolating, precision mixed, degassed, and frozen epoxy. It exhibits low shrinkage once cured and is ideal for gap filling purposes. This product is designed for structural bonding and staking applications where precise dispensing is required. 0161 conforms to HMS-2240 Type IX specifications and can be cured at room temperature.

Thermal Properties

(Based on cure of 1 hours @ 93°C)

Glass Transition Temp (°C)	87
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Outgassing Properties

(Based on cured of 1 hour @ 93°C)

TML (%)	0.27
CVCM (%)	0.01
WVR (%)	0.32

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